

PROGRAMME AT A GLANCE

Sunday June 17			
09.00-13.00	Tutorial 1: <u>Reliability Basics</u> , Olli Salmela, Nokia	(VIP Room)	
12.00-18.00	Setting up exhibition / On site registration		
14.00-18.00	Tutorial 3: <u>From Component Level to System-Level Reliability Estimates</u> , Olli Salmela, Nokia	(VIP Room)	Tutorial 4: <u>Embedded Chip SIP for Cost Effective 3D Packaging</u> , Chuck Bauer, TechLead Corp.
19.00-20.30	Welcome Cocktailparty at Oulu Town Hall		

	SESSION Room AUDITORIUM	SESSION ROOM SMALL AUDITORIUM	SESSION ROOM VINTTIKAMARI	POSTER PRESENTATIONS GROUND FLOOR VESTIBULE
Monday June 18				
09.00	OPENING			
09.10-10.40	INVITED PAPERS (3 pcs.)			
10.40-11.00	EXHIBITOR PRESENTATIONS (1 min each)			
11.00-21.00	Exhibition and Posters displayed			
11.00-11.20	COFFEE BREAK IN EXHIBITION AREA			
11.20-13.00	3D, SIP & embedded components 1	LTCC 1	NAMIS network: Nano and Micro systems 1 (Seoul Nat. University, École Polytechnique de Montreal, FEMTO)	POSTER1 (Optoelectronics, Medical, Design & Modelling)
	M-A-1A	M-A-1B	M-A-1C	
13.00-14.00	LUNCH BREAK IN EXHIBITION AREA	Optoelectronics 1	NAMIS network: Nano and Micro systems 2 (IMTEK, VTT, CIRMM)	POSTER2 (Sensors & MEMS packaging, Interconnection technologies, 3D, SIP & Embedded Components)
14.00 - 15.40	Advanced Packaging	M-P-1B	M-P-1C	
15.40-16.20	COFFEE BREAK IN EXHIBITION AREA	Global Business Council: Trends in the business! (Portelligent, Nokia, C-MAC, ZVEI)	Optoelectronics 2	
16.20-18.00 M-P-2A, M-P-2B	Manufacturing Technologies 1	M-P-2C	M-P-2B	
16.20-18.50 M-P-2C	M-P-2A			
19.00-21.00	Buffet Dinner in Exhibition Area			
Tuesday June 19				
09.00-17.00	Exhibition and Posters displayed			
09.00-10.40	Materials	European projects on embedding active and passives	Sensors & MEMS Packaging	
	T-A-1A	T-A-1C	T-A-1B	
10.40-11.20	COFFEE BREAK IN EXHIBITION AREA	LTCC 2		POSTER3 (Nano, Laminates & Quality, Leadfree & Green electronics)
11.20-13.00	3D, SIP & embedded components 2	T-A-2B		
	T-A-2A	RF		POSTER4 (Thermal management, Manufacturing technologies, Materials)
13.00-14.00	LUNCH BREAK IN EXHIBITION AREA	T-P-1B		
14.00 - 15.40	Interconnection technologies	T-P-2C	Laminates & Quality issues	
15.40-16.20	COFFEE BREAK IN EXHIBITION AREA	EU and International programmes	T-P-2B	
16.20-18.00 T-P-2A, T-P-2B	Manufacturing Technologies 2			
16.20-18.30 T-P-2C	T-P-2A			
19.00-23.00	Banquet Dinner at Maikkula mansion (bus transportation)			
Wednesday June 20				
09.00-11.30	Exhibition			
09.00-10.40	3D, SIP & embedded components 3	Thermal management & harsh environments		
	W-A-1A	W-A-1B		
10.40-11.20	COFFEE BREAK IN EXHIBITION AREA	Nano technologies		
11.20-13.00	Medical electronics & Applications	W-A-2B		
	W-A-2A			
13.00-13.30	CLOSING			
14.00-18.00			Tutorial 6: <u>LTCC (Low Temperature Cofired Ceramics) sensors, actuators and microsystems</u> , Leszek Golonka, Wroclaw Uni (Oulu Uni)	

11.30- Dismantling exhibition

Thursday June 21
NEMO Workshop More on: www.micro-optics.org